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Growth behavior and structural properties of titanium dioxide thin films on Si(100) and Si(111) substrates using single molecular precursor by high vacuum MOCVD

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We have deposited titanium dioxide (TiO2) thin films on Si(100) and Si(111) substrates at temperature in the range of 500 to 750 °C and at pressure in the range of $3.0\times10^{-7}\sim5.0\times10^{-5}$ Torr using a single molecular precursor such as titanium (IV) iso-propoxide (Ti[OCH(CH₃)₂]₄, 97%) by high vacuum metal-organic chemical vapor deposition (MOCVD) method. Highly oriented, stoichiometric TiO2 thin films with rutile phase were successfully deposited on both Si(100) and Si(111) substrates between 650 and 750 $^{\circ}$ C under the working pressure of 1.0×10 $^{\circ}$ Torr. XRD results clearly showed different growth behavior between Si(100) and Si(111) substrates. The main film growth directions are [110] on Si(100) and [200] on Si(111), respectively. SEM and TEM images showed a quite smooth surface with no cracks and sharp interface between film layers, suggesting good adhesion and uniformity in depth. In the case of TiO₂ films grown under low temperature below 600 °C and high pressure above 3.0×10 ⁵ Torr, TED pattern showed a mixed structure with spot and ring patterns, resulting in polycrystalline film formation. With increasing the growth temperature to 650 °C and decreasing the pressure to 3.0×10^{7} Torr, however, a strong spot images with weak ring pattern were observed, indicating that the film crystallinity as well as growth direction was strongly affected by deposition temperature and pressure.